

IGBT - Field Stop II NGTB40N65FL2WG

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop II Trench construction, and provides superior performance in demanding switching applications, offering both low on state voltage and minimal switching loss. The IGBT is well suited for UPS and solar applications. Incorporated into the device is a soft and fast co–packaged free wheeling diode with a low forward voltage.

Features

- Extremely Efficient Trench with Field Stop Technology
- $T_{Jmax} = 175$ °C
- Soft Fast Reverse Recovery Diode
- Optimized for High Speed Switching
- 5 µs Short-Circuit Capability
- These are Pb-Free Devices

Typical Applications

- Solar Inverters
- Uninterruptible Power Supplies (UPS)
- Welding

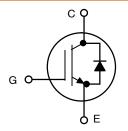
ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter Voltage	V _{CES}	650	V
Collector Current @ T _C = 25°C @ T _C = 100°C	I _C	80 40	A
Diode Forward Current @ T _C = 25°C @ T _C = 100°C	I _F	80 40	А
Diode Pulsed Current T _{PULSE} Limited by T _J Max	I _{FM}	160	Α
Pulsed Collector Current, T _{pulse} Limited by T _{Jmax}	I _{CM}	160	Α
Short–circuit Withstand Time V_{GE} = 15 V, V_{CE} = 400 V, $T_{J} \le +150^{\circ}C$	t _{SC}	5	μs
Gate-emitter Voltage	V_{GE}	±20	V
Transient Gate-emitter Voltage (T _{PULSE} = 5 μs, D < 0.10)		±30	٧
Power Dissipation @ T _C = 25°C @ T _C = 100°C	P _D	366 183	W
Operating Junction Temperature Range	TJ	–55 to +175	°C
Storage Temperature Range	T _{stg}	-55 to +175	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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40 A, 650 V V_{CEsat} = 1.7 V E_{off} = 0.44 mJ





MARKING DIAGRAM



40N65FL2 = Specific Device Code

A = Assembly Location Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB40N65FL2WG	TO-247 (Pb-Free)	30 Units / Rail

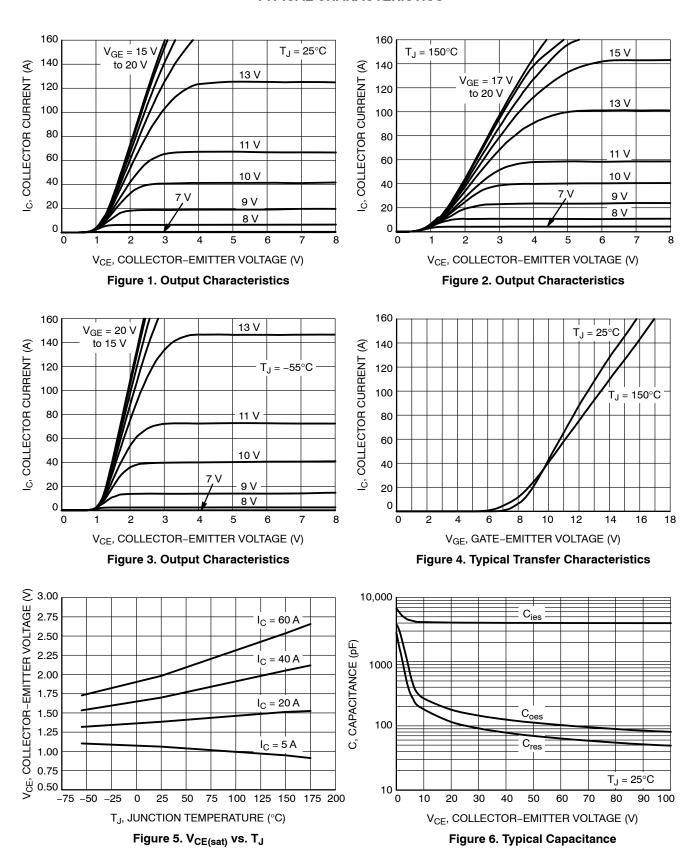
THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	0.41	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	1.00	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC						
Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0 \text{ V, I}_{C} = 500 \mu\text{A}$	V _{(BR)CES}	650	_	-	V
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 40 A V _{GE} = 15 V, I _C = 40 A, T _J = 175°C	V _{CEsat}	1.50 -	1.70 2.10	2.00	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 350 \mu A$	V _{GE(th)}	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	$V_{GE} = 0 \text{ V}, V_{CE} = 650 \text{ V}$ $V_{GE} = 0 \text{ V}, V_{CE} = 650 \text{ V}, T_{J=175^{\circ}\text{C}}$	I _{CES}	- -	- -	0.5 7.0	mA
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V , V _{CE} = 0 V	I _{GES}	-	_	200	nA
DYNAMIC CHARACTERISTIC	•			•		•
Input capacitance		C _{ies}	-	4060	-	pF
Output capacitance	V _{CE} = 20 V, V _{GE} = 0 V, f = 1 MHz	C _{oes}	_	179	-	
Reverse transfer capacitance	1	C _{res}	_	115	-	
Gate charge total		Qg	-	170	-	nC
Gate to emitter charge	V _{CE} = 480 V, I _C = 40 A, V _{GE} = 15 V	Q _{ge}	_	41	-	
Gate to collector charge	1	Q _{gc}	_	87	-	
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD			•		
Turn-on delay time		t _{d(on)}	-	84	-	ns
Rise time	1	t _r	_	40	-	
Turn-off delay time	T _J = 25°C	t _{d(off)}	_	177	-	
Fall time	$V_{CC} = 400 \text{ V}, I_{C} = 40 \text{ A}$ $R_{q} = 10 \Omega$	t _f	_	70	-	
Turn-on switching loss	$V_{GE} = 0 \text{ V} / 15 \text{ V}$	E _{on}	-	0.97	-	mJ
Turn-off switching loss	1	E _{off}	_	0.44	-	
Total switching loss	1	E _{ts}	_	1.41	-	
Turn-on delay time		t _{d(on)}	_	82	-	ns
Rise time	1	t _r	_	40	-	
Turn-off delay time	T _J = 150°C	t _{d(off)}	_	183	-	
Fall time	$V_{CC} = 400 \text{ V}, I_{C} = 40 \text{ A}$ $R_{g} = 10 \Omega$	t _f	_	93	-	
Turn-on switching loss	V _{GE} = 0 V/ 15 V	E _{on}	_	1.20	-	mJ
Turn-off switching loss	1	E _{off}	-	0.76	-	
Total switching loss	1	E _{ts}	-	1.96	-	
DIODE CHARACTERISTIC				•		•
Forward voltage	V _{GE} = 0 V, I _F = 40 A V _{GE} = 0 V, I _F = 40 A, T _J = 175°C	V _F	1.50 -	2.20 2.40	2.90 -	V
Reverse recovery time	T _{.1} = 25°C	t _{rr}	_	72	-	ns
Reverse recovery charge	$I_F = 40 \text{ Å}, V_R = 200 \text{ V}$	Q _{rr}	_	275	-	nC
Reverse recovery current	di _F /dt = 200 A/μs	I _{rrm}	_	6.7	-	Α
Reverse recovery time	T ₁ = 175°C	t _{rr}	_	158	-	ns
Reverse recovery charge	$I_F = 40^{\circ} A$, $V_R = 400 \text{ V}$	Q _{rr}	_	980	-	nC
Reverse recovery current	di _F /dt = 200 A/μs	I _{rrm}	_	8.5	_	Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



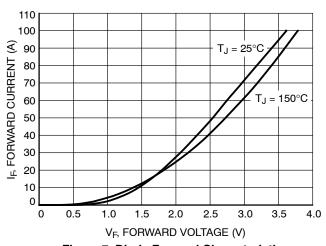


Figure 7. Diode Forward Characteristics

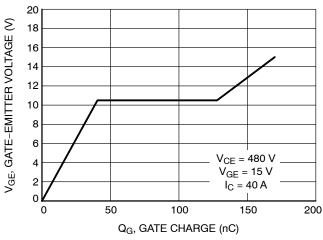


Figure 8. Typical Gate Charge

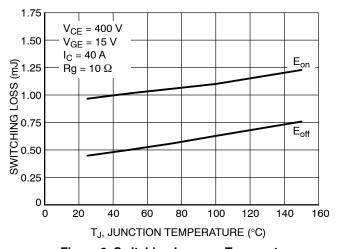


Figure 9. Switching Loss vs. Temperature

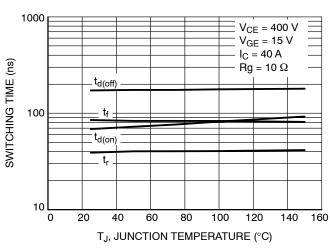
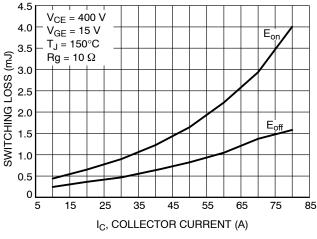


Figure 10. Switching Time vs. Temperature





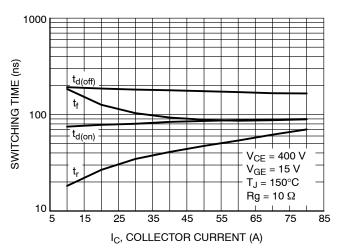


Figure 12. Switching Time vs. I_C

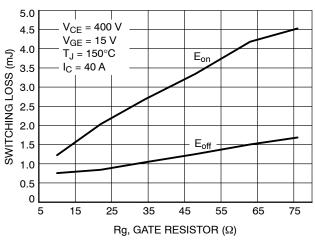


Figure 13. Switching Loss vs. Rg

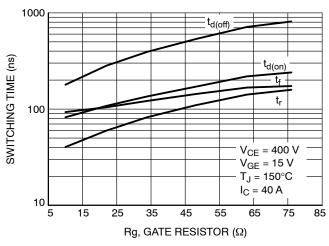


Figure 14. Switching Time vs. Rg

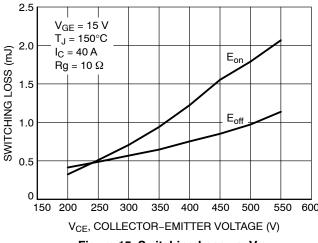


Figure 15. Switching Loss vs. V_{CE}

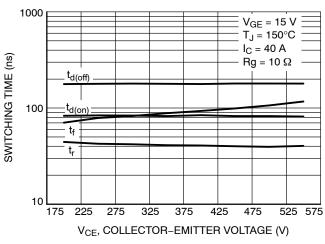


Figure 16. Switching Time vs. V_{CE}

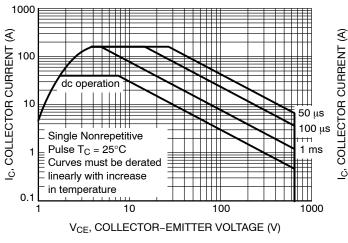


Figure 17. Safe Operating Area

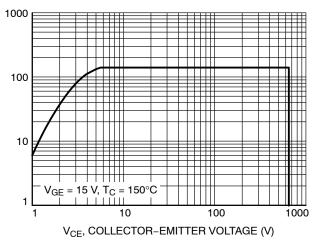
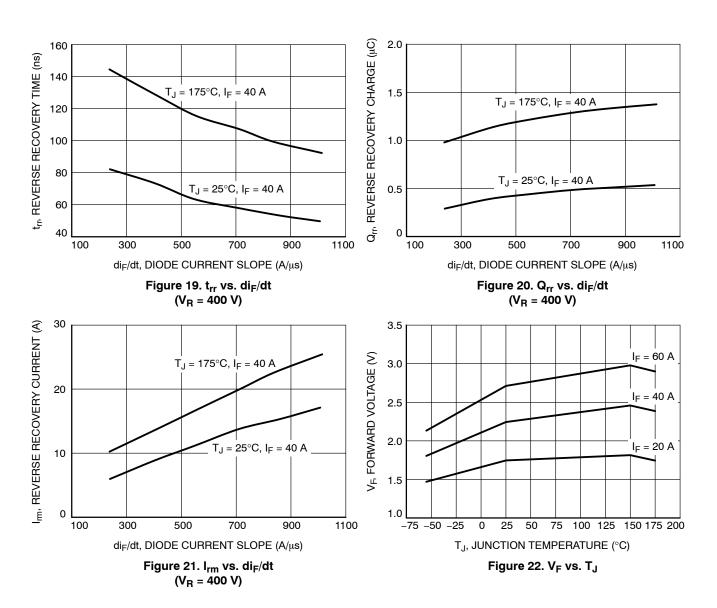


Figure 18. Reverse Bias Safe Operating Area



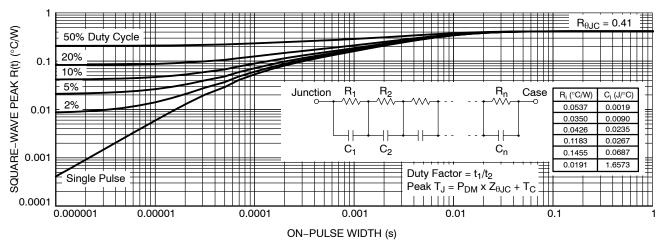


Figure 23. IGBT Transient Thermal Impedance

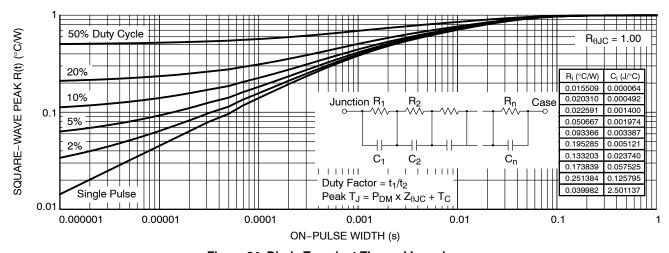


Figure 24. Diode Transient Thermal Impedance

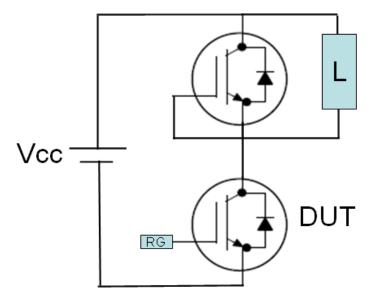


Figure 25. Test Circuit for Switching Characteristics

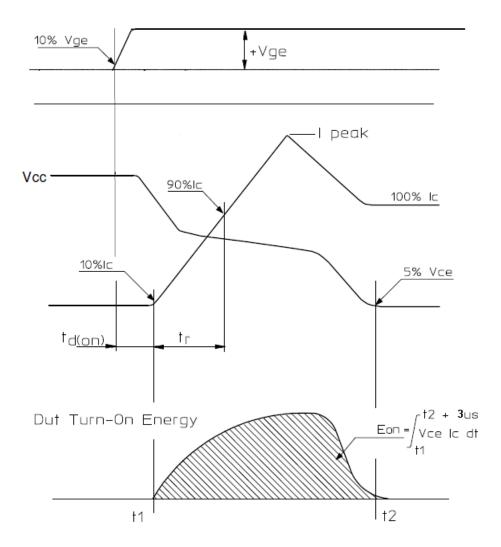


Figure 26. Definition of Turn On Waveform

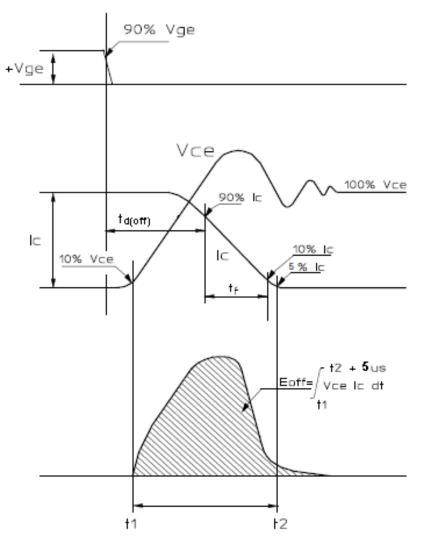
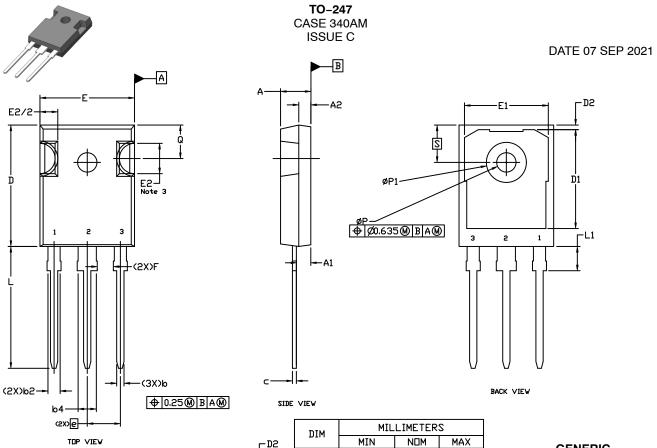
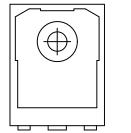
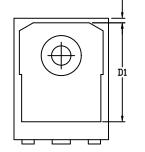


Figure 27. Definition of Turn Off Waveform



Α





NOTE 4 HEATSINK SHAPES

NOTES:

- 1. DIMENSIONING AND TOLERANCE AS PER ASME Y14.5M, 2009.
- 2. ALL DIMENSION ARE IN MILLIMETERS.
- SLOT REQUIRED, NOTCH MAY BE ROUNDED. 3.
- OPTIONAL BACK SIDE HEATSINK SHAPE.
- DIMENSIONS ARE EXCLUSIVE OF BURRS AND MOLD FLASH.
 DIMENSIONS D AND E ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
- 6. DIMENSIONS AT TO BE MEASURED IN THE REGION DEFINED BY L1.
- 7. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

A1	2,20	2.40	2.60
A2	1.80	2.00	2.20
b	1.07	1.20	1.33
b2	1.65	2.12	2.35
b4	2.60	3.12	3.40
C	0.45	0.60	0.75
D	20.80	21.00	21.34
D1	16.30		
D2	0.75		
E	15.50	16.00	16.25
E1	13.80		
E2	4.32	4.90	5.49
e	5.45 BSC		
F	2.655	2.655	
L	19.80	20.00	20.80

4.70

5.30

5.00

⊐∟	0.75		
Ε	15.50	16.00	16.25
E1	13.80		
E2	4.32	4.90	5.49
е	5.45 BSC		
F	2.655		
L	19.80	20.00	20.80
L1	3.81	4.20	4.35
Р	3.55	3.60	3.65
P1	6.60		
Q	5.40	6.00	6.20
2	6.15 BSC		

GENERIC MARKING DIAGRAMS*





XXXX = Specific Device Code = Assembly Location

Υ = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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